Triacs logic level

BT137X-600D

GENERAL DESCRIPTION

Passivated, sensitive gate triac in a full pack plastic envelope, intended for use in general purpose bidirectional switching and phase control applications. This device is intended to be interfaced directly to microcontrollers, logic integrated circuits and other low

QUICK REFERENCE DATA

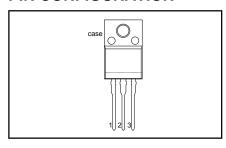
SYMBOL	PARAMETER		UNIT
V _{DRM}	Repetitive peak off-state voltages	600	V
I _{T(RMS)}	RMS on-state current	8	A
I _{TSM}	Non-repetitive peak on-state current	65	A

PINNING - SOT186A

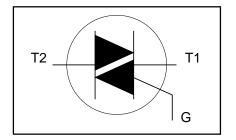
power gate trigger circuits.

PIN	DESCRIPTION			
1	main terminal 1			
2	main terminal 2			
3	gate			
case	isolated			

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DRM}	Repetitive peak off-state		-	600 ¹	V
I _{T(RMS)}	voltages RMS on-state current	full sine wave; T _{hs} ≤ 73 °C	-	8	А
I _{TSM}	Non-repetitive peak on-state current	full sine wave; $T_j = 25$ °C prior to surge $t = 20$ ms	_	<u>6</u> 5	A
l²t dl⊤/dt	I ² t for fusing Repetitive rate of rise of	t = 16.7 ms t = 10 ms $I_{TM} = 12 \text{ A}; I_G = 0.2 \text{ A};$	-	71 21	A A ² s
ui / ut	on-state current after triggering	$dl_{G}/dt = 0.2 \text{ A}/\mu\text{s}$ $T2+ G+$	-	50	A/μs
		T2+ G- T2- G- T2- G+	- - -	50 50 10	A/μs A/μs A/μs
$egin{align} I_{ ext{GM}} \ V_{ ext{GM}} \ P_{ ext{GM}} \ \end{array}$	Peak gate current Peak gate voltage Peak gate power		- - -	2 5 5	Å V W
$P_{G(AV)}$ T_{stg}	Average gate power Storage temperature Operating junction temperature	over any 20 ms period	-40 -	0.5 150 125	Č C C

June 2001 1 Rev 1.000

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 A/µs.

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ISOLATION LIMITING VALUE & CHARACTERISTIC

 T_{hs} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65%; clean and dustfree	ı	ı	2500	V
C _{isol}	Capacitance from T2 to external heatsink	f = 1 MHz	ı	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{\text{th } j\text{-hs}}$ $R_{\text{th } i\text{-a}}$	Thermal resistance	full or half cycle with heatsink compound without heatsink compound in free air		- - 55	4.5 6.5	K/W K/W K/W
	junction to ambient					

STATIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

ij = 23 O urijess otrierwise stated						
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{GT}	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$				
01		T2+ G+	-	2.5	5	mΑ
		T2+ G-	-	3.5	5 5	mΑ
		T2- G-	-	3.5	5	mΑ
		T2- G+	-	6.5	10	mΑ
I _L	Latching current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$				
-		T2+ G+	-	1.6	15	mΑ
		T2+ G-	-	8.5	20	mΑ
		T2- G-	-	1.2	15	mΑ
		T2- G+	-	2.5	20	mΑ
l _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	1.5	10	mΑ
V_{T}	On-state voltage	$I_{T} = 10 \text{ A}$	-	1.3	1.65	V
V _{GT}	Gate trigger voltage	$\dot{V}_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}$	-	0.7	1.5	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_i = 125 ^{\circ}\text{C}$	0.25	0.4	-	V
I _D	Off-state leakage current	$V_D = V_{DRM(max)}$; $T_j = 125$ °C	-	0.1	0.5	mA

DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)}; T_j = 125 °C;$ exponential waveform; $R_{GK} = 1 k\Omega$	-	5	-	V/µs
t _{gt}	Gate controlled turn-on time	$I_{TM} = 12 \text{ A}; V_D = V_{DRM(max)}; I_G = 0.1 \text{ A}; dI_G/dt = 5 \text{ A}/\mu\text{s}$	-	2	-	μs

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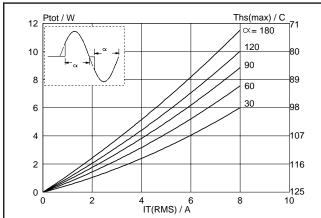


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where $\alpha =$ conduction angle.

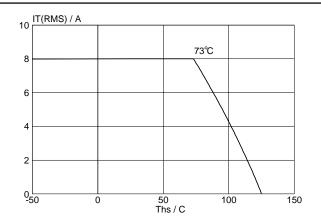


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus heatsink temperature T_{hs} .

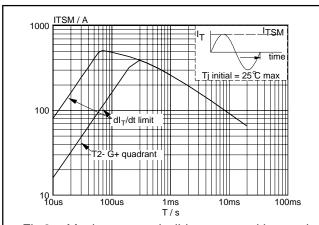


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

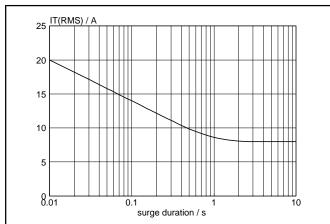


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{hs} \le 73$ °C.

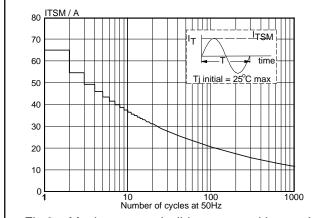


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

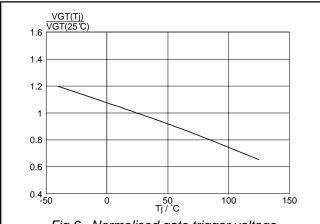
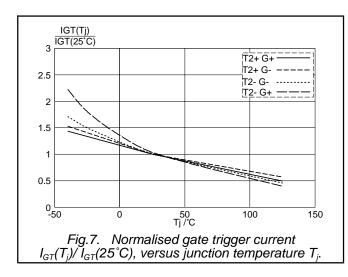
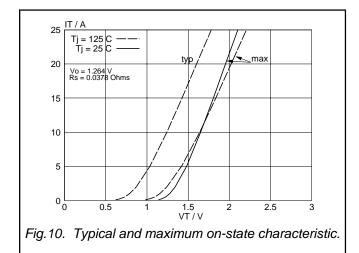
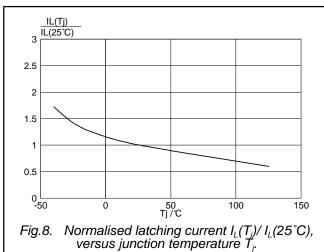


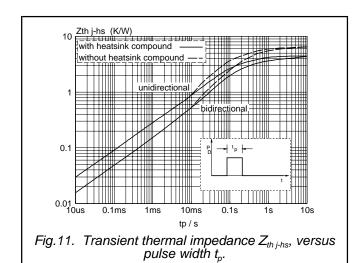
Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$, versus junction temperature T_j .

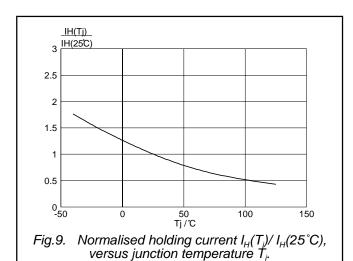
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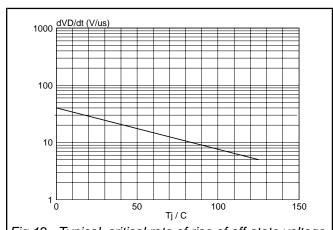
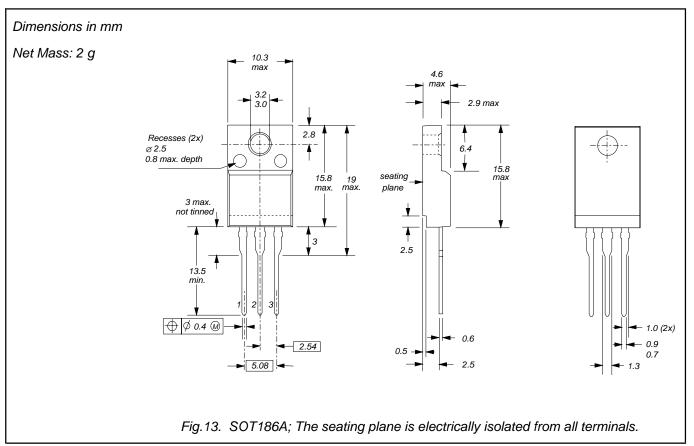


Fig.12. Typical, critical rate of rise of off-state voltage, dV_D/dt versus junction temperature T_i.

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MECHANICAL DATA



- Refer to mounting instructions for F-pack envelopes.
 Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

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DEFINITIONS

DATA SHEET STATU	DATA SHEET STATUS					
DATA SHEET STATUS ²	PRODUCT STATUS ³	DEFINITIONS				
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice				
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in ordere to improve the design and supply the best possible product				
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A				
Limiting values						

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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